



Product Change Notification: JAON-04FGFZ246

Date:

24-Aug-2026

Product Category:

Linear Regulators

Notification Subject:

CCB 7962 Final Notice: Qualification of MTAI as an additional assembly site for selected MIC5205, MIC5207 and MIC5219 device families available in 5L SOT-23 package.

Affected CPNs:

[JAON-04FGFZ246_Affected_CPN_08242026.pdf](#)

[JAON-04FGFZ246_Affected_CPN_08242026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for selected MIC5205, MIC5207 and MIC5219 device families available in 5L SOT-23 package.

Pre and Post Summary Changes:

	Pre Change		Post Change			Change (Yes/No)
Assembly Site	Stars Microelectronics (Thailand) Public Company Limited (STAR)	Unisem (M) Berhad Perak, Malaysia (UNIS)	Stars Microelectronics (Thailand) Public Company Limited (STAR)	Unisem (M) Berhad Perak, Malaysia (UNIS)	Microchip Technology Thailand (HQ) (MTAI)	Yes

Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date													X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

December 24, 2025: Issued initial notification.

March 17, 2026: Issued final notification. Attached the Qualification Report. Provided the estimated first ship date to be on April 17, 2026.

August 24, 2026: Re-issued final notification. Updated the image in the Pre and Post Change Summary attachment from 'Top Marking' to 'Top Marking Pattern Change.'

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_JAON-04FGFZ246_Qualification Report.pdf](#)

[PCN_JAON-04FGFZ246_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MIC5207YM5-TX

MIC5219YM5-TX

MIC5205-2.85YM5-TR

MIC5205-2.8YM5-TR

MIC5205-2.9YM5-TR

MIC5205-3.0YM5-TR

MIC5205-3.3YM5-TR

MIC5205-3.3YM5-TR-HCM

MIC5205-3.6YM5-TR

MIC5205-3.8YM5-TR

MIC5205-4.0YM5-TR

MIC5219-2.5YM5-TR

MIC5219-2.5YM5-TX

MIC5219-2.6YM5-TR

MIC5205YM5-TR

MIC5219-2.8YM5-TR

MIC5207-1.8YM5-TX

MIC5219-3.3YM5-TR

MIC5205-3.1YM5-TR

MIC5207-2.5YM5-TR

MIC5207-2.5YM5-TX

MIC5219-2.9YM5-TR

MIC5219-3.0YM5-TR

MIC5205-2.5YM5-TR

MIC5205-2.5YM5-TX

MIC5205-2.7YM5-TR

MIC5207-2.9YM5-TR

MIC5207-3.0YM5-TR

MIC5207-3.1YM5-TR

MIC5207-3.2YM5-TR

MIC5207-3.3YM5-TR

MIC5219-3.1YM5-TR

MIC5219-3.3YM5-TX

MIC5207-3.3YM5-TX

MIC5207-4.0YM5-TR

MIC5207-5.0YM5-TX

MIC5207YM5-TR

MIC5219-5.0YM5-TR

MIC5219YM5-TR

MIC5207-1.8YM5-TR

MIC5207-5.0YM5-TR

MIC5219-3.6YM5-TR

MIC5205-3.2YM5-TR

MIC5205-5.0YM5-TR

MIC5205YM5-TX

MIC5219-2.7YM5-TR

MIC5219-2.85YM5-TR

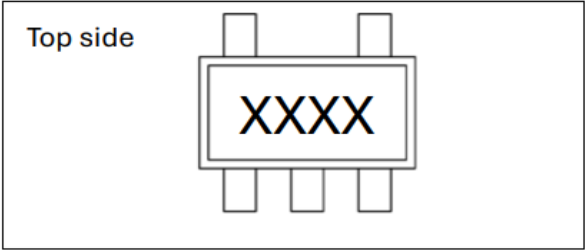
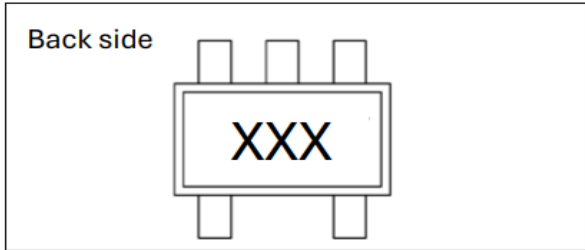
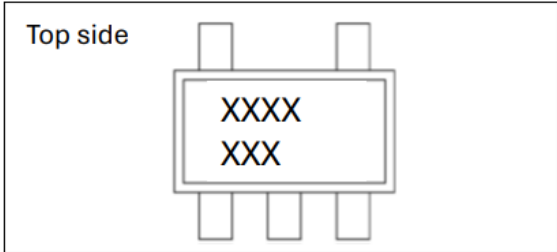
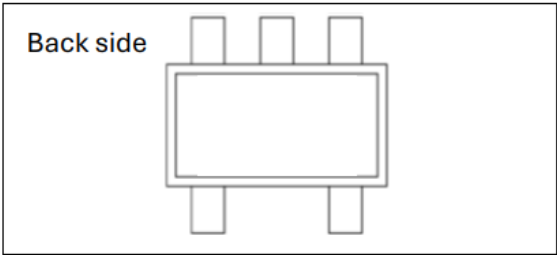
MIC5207-2.8YM5-TR

CCB 7962
Pre and Post Change Summary
PCN #: JAON-04FGFZ246

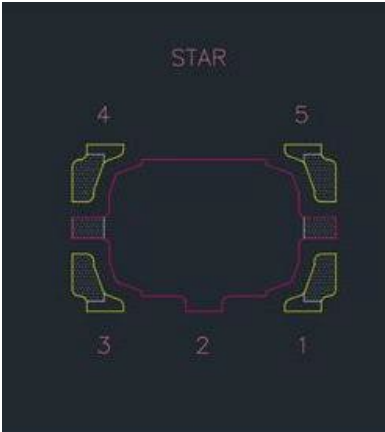
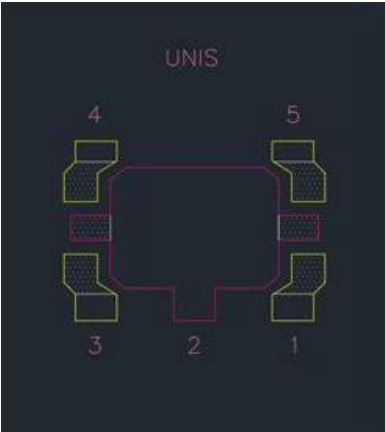
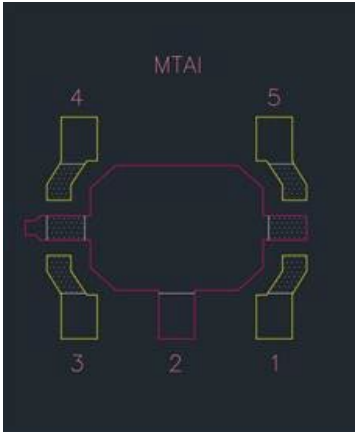


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Top Marking Pattern Change

STAR / UNIS	MTAI
Marking 4 characters on Top side And marking 3 characters on Back side Top side  Back side 	Marking 7 characters (2 Lines) on Top side No marking on Back side Top side  Back side 

Lead Frame Comparison

STAR	UNIS	MTAI
		



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: JAON-04FGFZ246

Date:
March 10, 2026

**Qualification of MTAI as an additional assembly site for
selected MIC5205, MIC5207 and MIC5219 device families
available in 5L SOT-23 package.**



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for selected MIC5205, MIC5207 and MIC5219 device families available in 5L SOT-23 package.
CN	E000293506
QUAL ID	R2501585 Rev. A
Bonding No.	BD-003980 Rev.01
MP CODE	216A1YC7XBA1
Part No.	MIC5205YM5-TR
CCB No.	7962
<u>Lead Frame</u>	
Paddle size	66 x 48
Material	CDA194
Surface	Bare Cu
Process	Stamped
Lead lock	No
Part number	10100505
Plating composition	Matte Tin
<u>Bond Wire</u>	
Wire	CuPdAu wire
<u>Die Attach Material</u>	
Epoxy	CRM-1064L
<u>Mold Compound</u>	
Mold compound	G634A
<u>Package</u>	
Type	5L SOT-23



MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI263600771.000	MCSO525426750.112	2549VRH
MTAI263601136.000	MCSO525426750.112	2549VRH
MTAI263601116.000	MCSO525426750.112	2549WW3

Result ☒ Pass ☐ Fail ☐ _____

5L SOT-23 assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test: +25°C System: TMT_MCRS_NT	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C System: TMT_MCRS_NT		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_MCRS_NT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_MCRS_NT		231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 20 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_MCRS_NT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven Electrical Test: +25°C System: TMT_MCRS_NT	JESD22-A103	135(0)	135 0/135	Pass	45 units /lots
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	22 0/22	Pass	
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>3.00 grams) Bond Shear (>12.60 grams)	Mil. Std. 883-2011 CDF-AEC- Q100-001	30(0) Wires 30(0) Bonds	0/30 0/30	Pass Pass	